

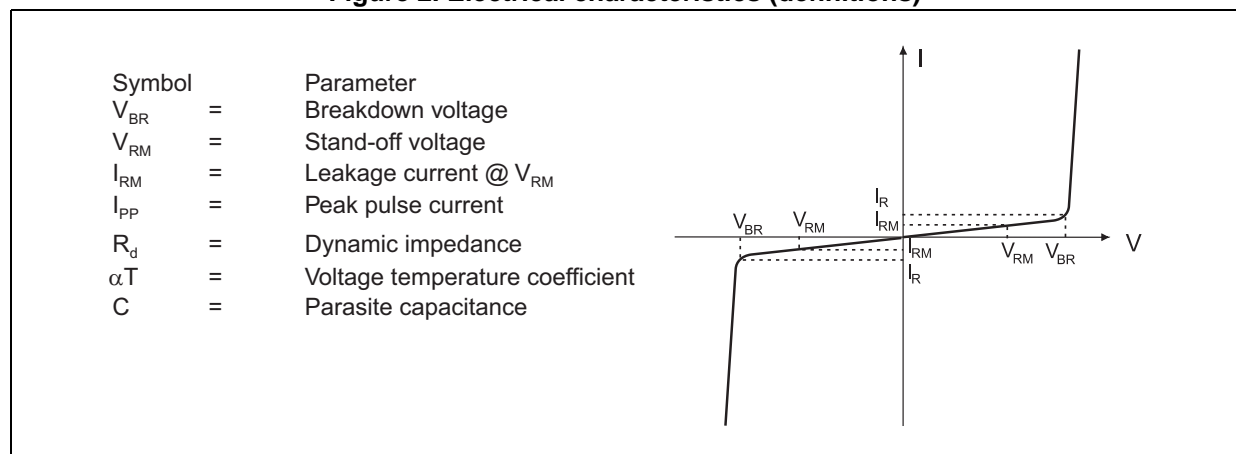
# 1 Characteristics

**Table 1. Absolute maximum ratings ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ )**

Symbol	Parameter	Value	Unit
$V_{PP}$	Peak pulse voltage: IEC 61000-4-2 contact discharge IEC 61000-4-2 air discharge	8 20	kV
$P_{PP}$	Peak pulse power (8/20 $\mu\text{s}$ )	20	W
$I_{PP}$	Peak pulse current (8/20 $\mu\text{s}$ )	1.5	A
$T_j$	Operating junction temperature range	-40 to +150	$^{\circ}\text{C}$
$T_{stg}$	Storage temperature range	-65 to +150	$^{\circ}\text{C}$
$T_L$	Maximum lead temperature for soldering during 10 s	260	$^{\circ}\text{C}$

**Note:** For a surge greater than the maximum values, the diode will fail in short-circuit

**Figure 2. Electrical characteristics (definitions)**



**Table 2. Electrical characteristics (values,  $T_{amb} = 25\text{ }^{\circ}\text{C}$ )**

Symbol	Test Condition	Min.	Typ.	Max.	Unit
$V_{BR}$	$I_R = 1\text{ mA}$	5	6.6		V
$I_{RM}$	$V_{RM} = 3.6\text{ V}$		5	100	nA
$V_{CL}$	$I_{PP} = 1\text{ A}, 8/20\text{ }\mu\text{A}$		10	12	V
$R_d$	Dynamic resistance, pulse duration 100 ns		1.3		$\Omega$
$C_{line}$	$F = (200\text{ MHz}- 3000\text{ MHz}), V_R = 0\text{ V}$		0.2	0.3	pF
fc	-3 dB		30		GHz

Figure 3. Leakage current versus junction temperature (typical values)

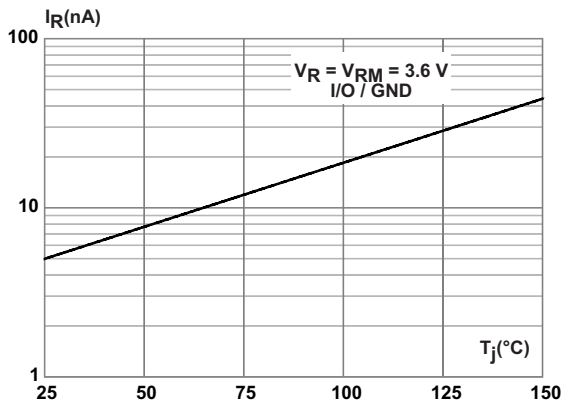


Figure 4. Junction capacitance versus frequency (typical values)

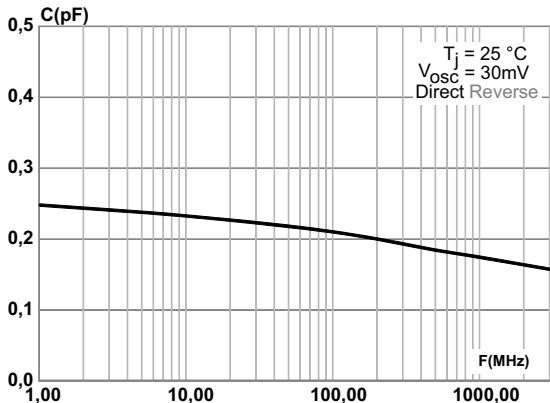


Figure 5. ESD response to IEC 61000-4-2 (+8 kV contact discharge)

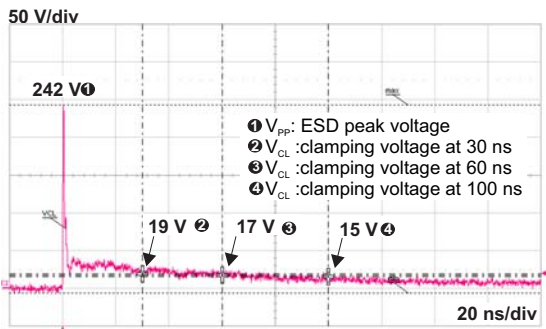


Figure 6. JESD response to IEC 61000-4-2 (-8 kV contact discharge)

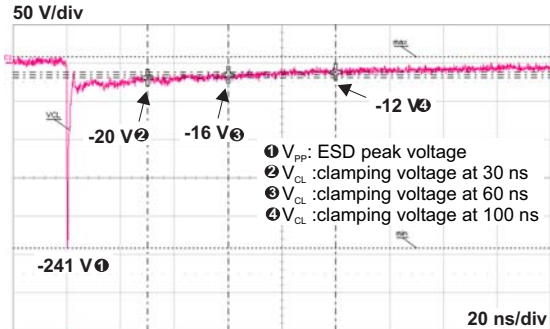


Figure 7. S21 attenuation measurement results

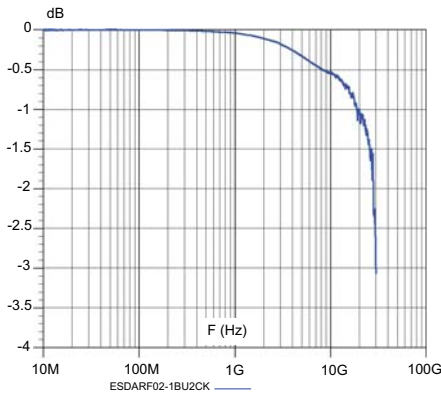
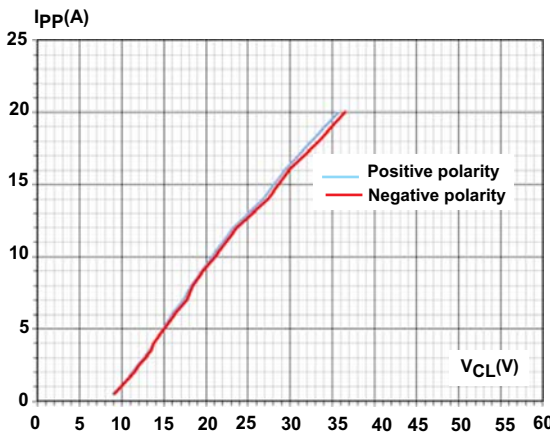


Figure 8. TLP measurements



## 2 Package information

- Epoxy meets UL94, V0
- Bar indicates pin 1

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 2.1 ST0201 package information

Figure 9. ST0201 package outline

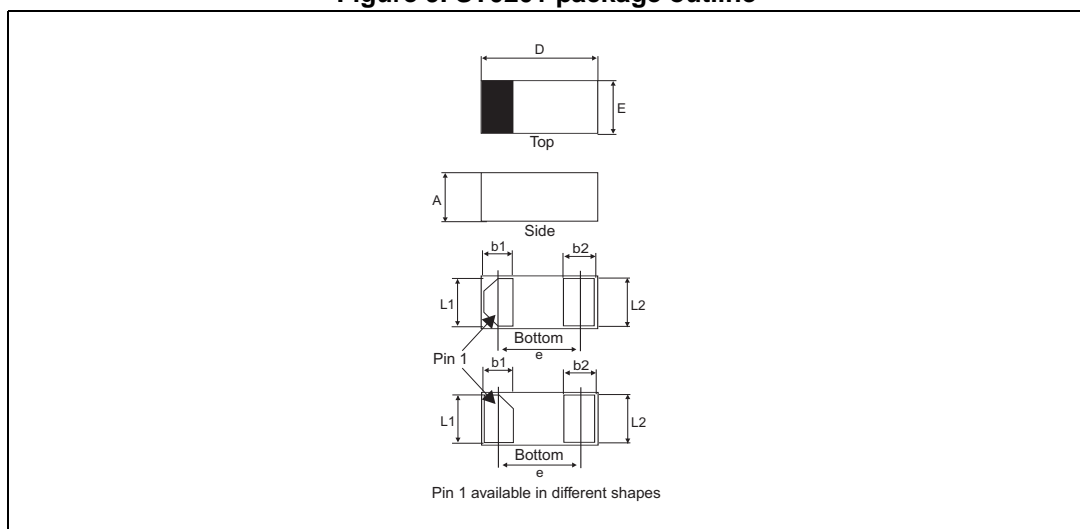
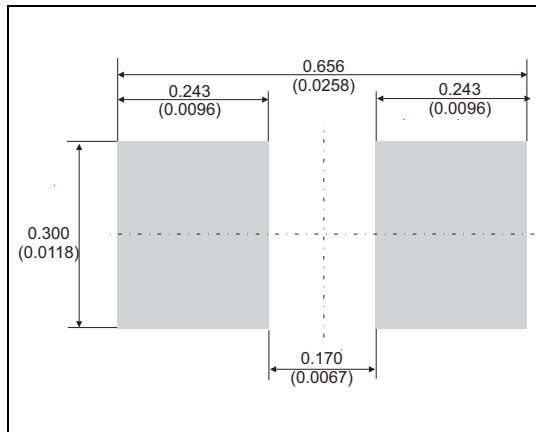


Table 3. 0201 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.23	0.28	0.33	0.0091	0.0110	0.0130
b1	0.20	0.25	0.30	0.0079	0.0098	0.0118
b2	0.20	0.25	0.30	0.0079	0.0098	0.0118
D	0.55	0.60	0.65	0.0217	0.0236	0.0256
E	0.25	0.30	0.35	0.0099	0.0118	0.0138
e		0.35			0.0138	
L1	0.13	0.18	0.23	0.0052	0.0071	0.0091
L2	0.14	0.19	0.24	0.0055	0.0075	0.0095

**Figure 10. Footprint, dimensions in mm  
(inches)**



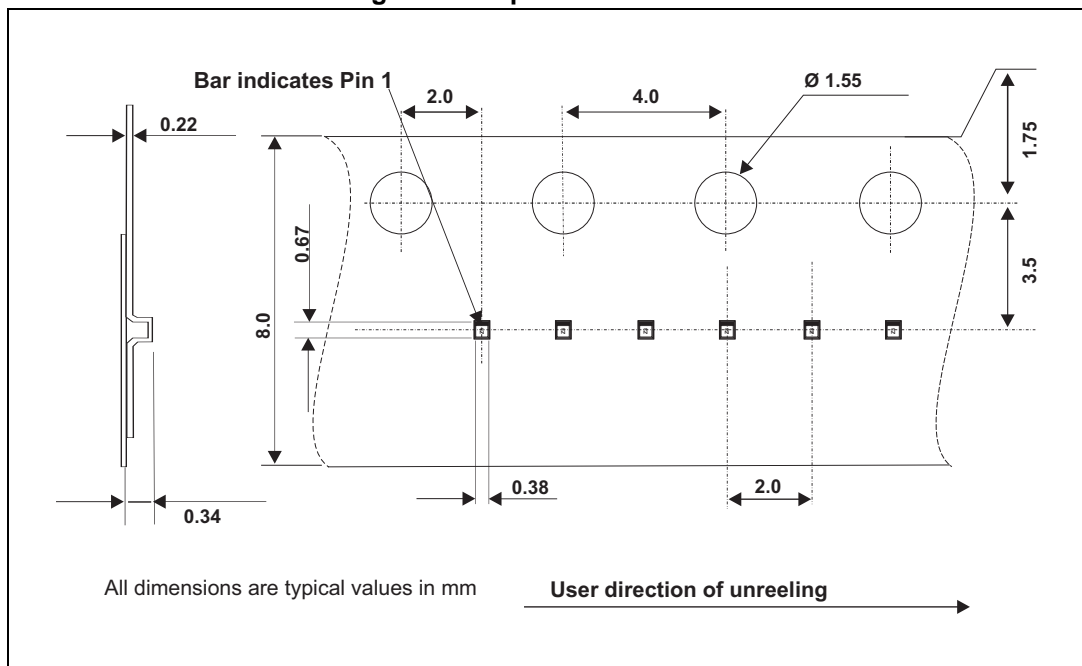
### Figure 11. Marking



*Note:*

*Product marking may be rotated by 180° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.*

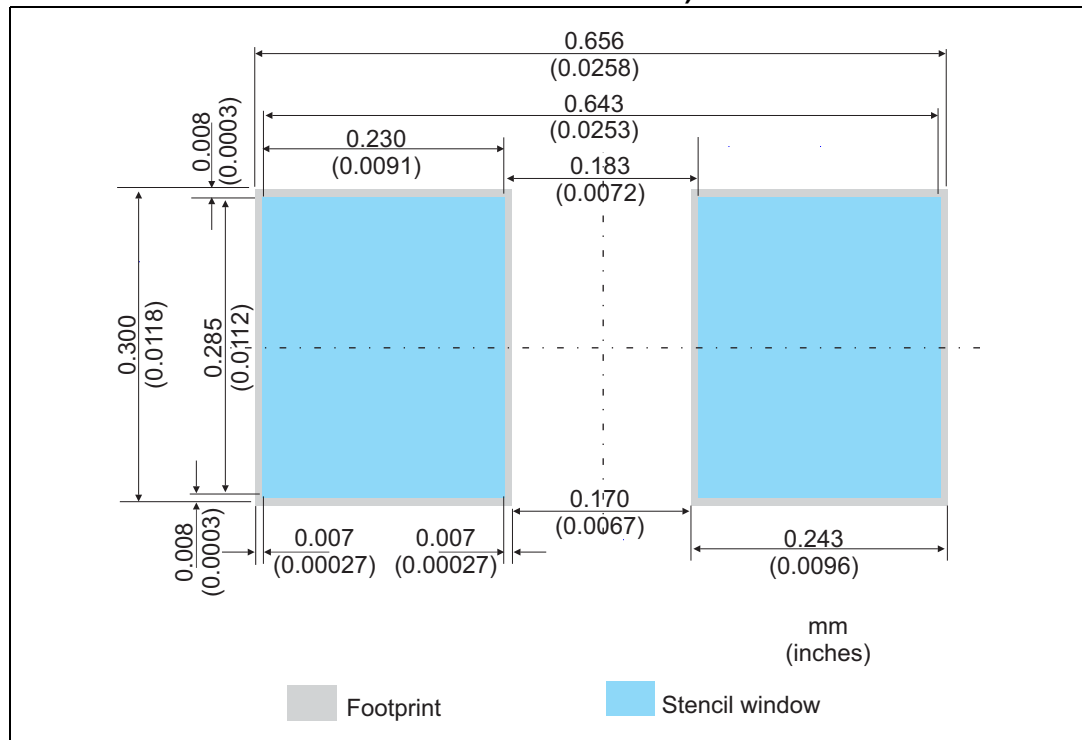
### Figure 12. Tape and reel outline



### 3 Recommendation on PCB assembly

#### 3.1 Stencil opening design

Figure 13. Recommended stencil windows-opening 90%/Thickness 80µm (all dimensions are in mm)



#### 3.2 Solder paste

1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
2. "No clean" solder paste is recommended.
3. Offers a high tack force to resist component displacement during PCB movement.
4. Use solder paste with fine particles: Type4 (powder particle size is 20-45 µm).

### 3.3 Placement

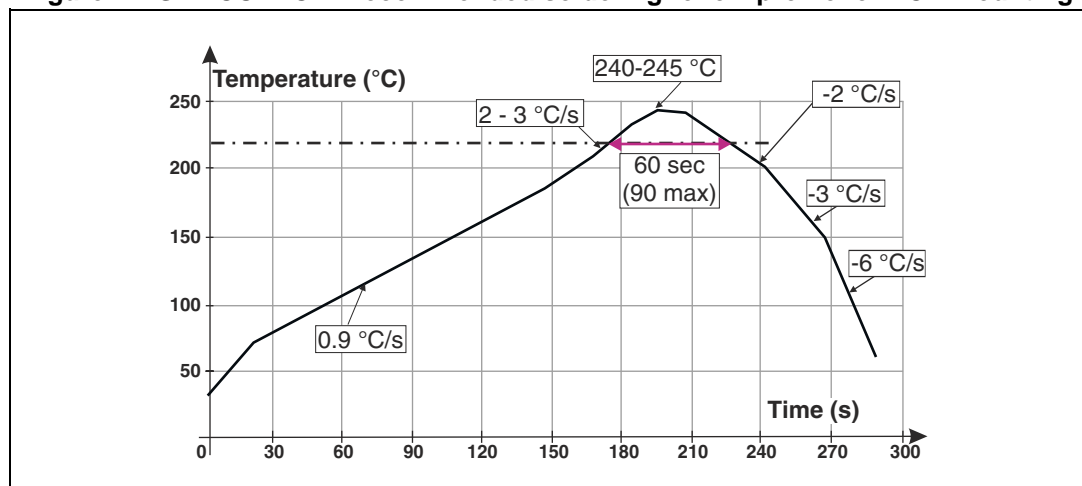
1. Manual positioning is not recommended.
2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
3. Standard tolerance of  $\pm 0.05$  mm is recommended.
4. 1.0 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

### 3.4 PCB design preference

1. To control the solder paste amount, the closed via is recommended instead of open vias.
2. The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

### 3.5 Reflow profile

Figure 14. ST ECOPACK® recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

## 4 Ordering information

Figure 15. Ordering information scheme

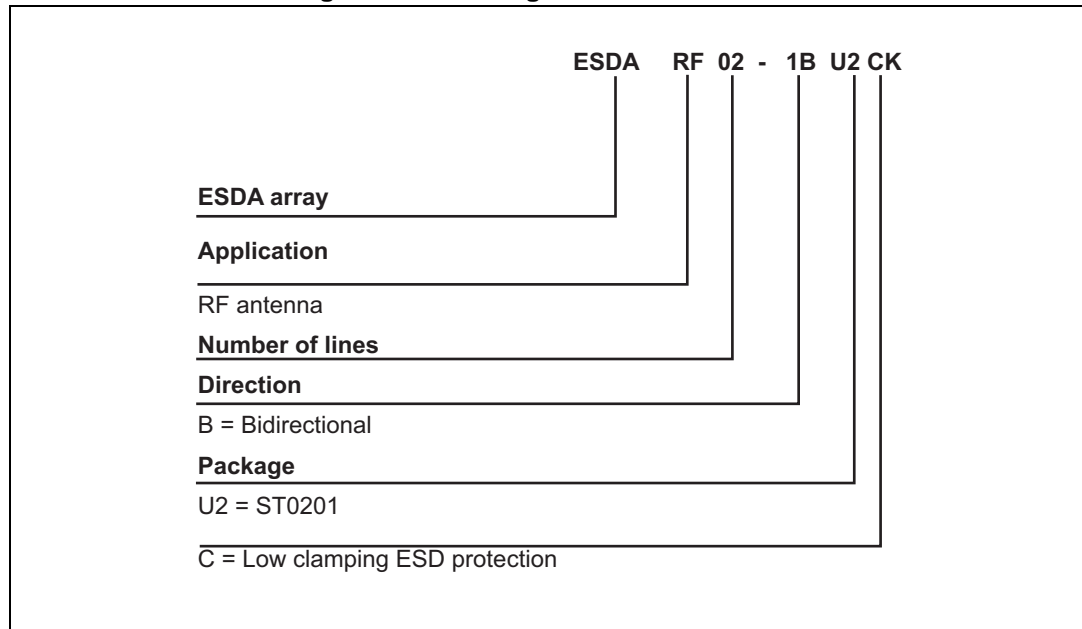


Table 4. Ordering information

Order code	Marking	Weight	Base qty.	Delivery mode
ESDARF02-1BU2CK	Z3 <sup>(1)</sup>	0.124 mg	15000	Tape and reel

1. The marking can be rotated by 180° to differentiate assembly location

## 5 Revision history

Table 5. Document revision history

Date	Revision	Changes
25-Feb-2015	1	Initial release.
02-Jun-2016	2	Updated <i>Features</i> . Updated <i>Table 2</i> and reformatted to current standard.
23-Jan-2017	3	Updated <i>Table 3</i> .

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